



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: **HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF MANUFACTURING THE PACKAGE**

RESPONSE TO ELECTION REQUIREMENT AND
AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This Amendment and Response is submitted in response to the Office Action dated December 28, 2004, in which Examiner set a shortened statutory period for reply of one month, making a response timely if filed before or on January 28, 2005.

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